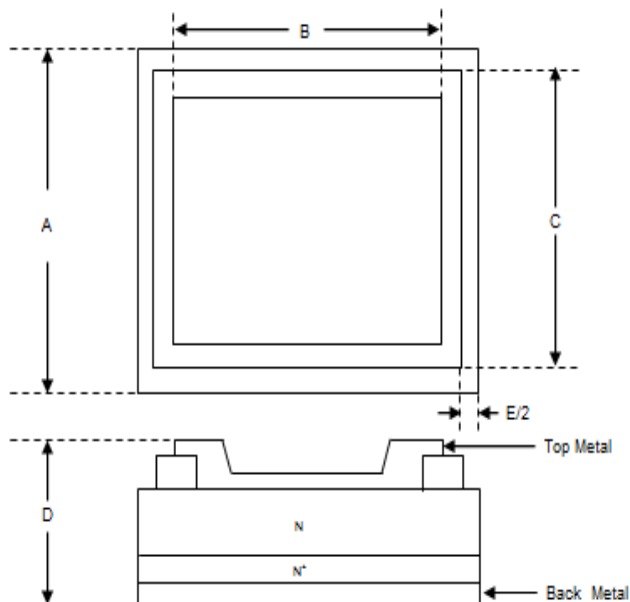


Trench Schottky Barrier Diode Wafer (TSBD)



Item	Dimensions	
	um	mil
Die Size (A)	710	28
Top Metal Pad Size (B)	610	26
Passivation Seal (C)	660	55.7
Wafer Thickness (D)	200	8
Scribe Line Width (E)	50	2
Other Informations		
Wafer Size	6"	
Gross Die	31250	
Top Metal	Ag	
Back Metal	Ag	

Electrical Characteristics @TA=25°C				
Item	Symbol	Spec. Limit	Die Sort	Unit
Maximum Repetitive Peak Reverse Voltage @0.1mA	V_{RRM}	60	64	V
Maximum Average Forward Rectified Current	I_O	2	-	A
Forward Voltage Drop, @ $I_F=1A$ @ $I_F=2A$	V_F	0.48 0.60	0.46 -	V
Maximum Reverse Current at Rated V_{RRM}	I_R	60	45	μA
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	20	-	A
Operating Temperature Range	T_J	-50 to +125	-	°C
Storage Temperature Range	T_{STG}	-50 to +150	-	°C